

74F240, 74F244

Octal Buffers/Line Drivers with 3-STATE Outputs

Features

- 3-STATE outputs drive bus lines or buffer memory address registers
- Outputs sink 64mA (48mA mil)
- 12mA source current
- Input clamp diodes limit high-speed termination effects

General Description

The 74F240 and 74F244 are octal buffers and line drivers designed to be employed as memory and address drivers, clock drivers and bus-oriented transmitters/receivers which provide improved PC and board density.

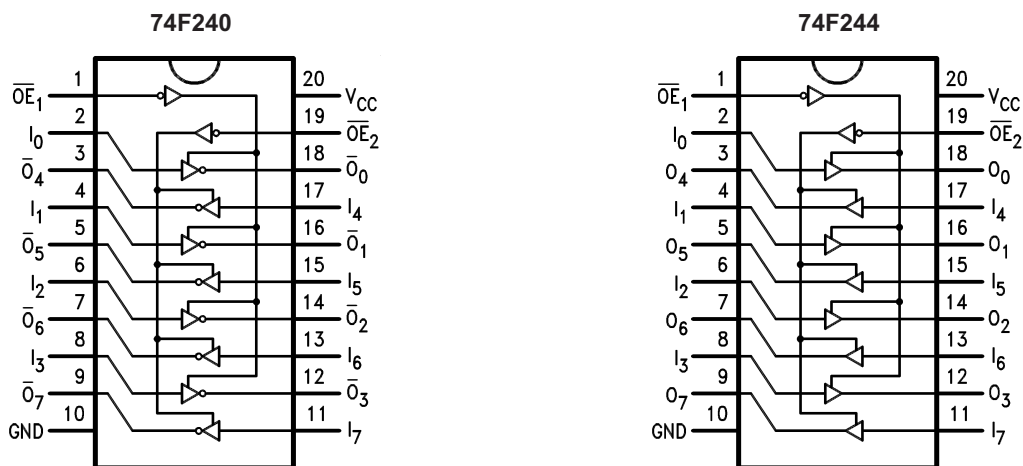
Ordering Information

Order Code	Package Number	Package Description
74F240SC ⁽¹⁾	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74F240SJ ⁽¹⁾	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74F240PC	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide
74F244SC ⁽¹⁾	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74F244SJ ⁽¹⁾	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74F244MSA ⁽¹⁾	MSA20	20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide
74F244PC	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

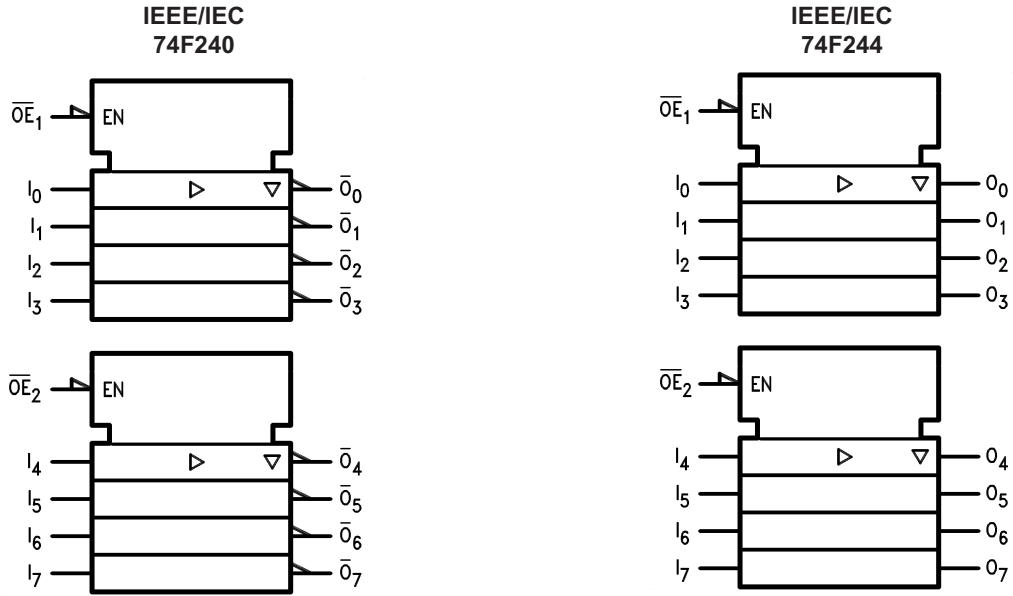
Note:

1. Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering number.

Connection Diagrams



Logic Symbols



Unit Loading/Fan Out

Pin Names	Description	U.L. HIGH/LOW	Input I_{IH} / I_{IL} , Output I_{OH} / I_{OL}
$\overline{OE}_1, \overline{OE}_2$	3-STATE Output Enable Input (Active LOW)	1.0 / 1.667	20 μ A / -1mA
OE_2	3-STATE Output Enable Input (Active HIGH)	1.0 / 1.667	20 μ A / -1mA
I_0 - I_7	Inputs (74F240)	1.0 / 1.667 ⁽²⁾	20 μ A / -1mA
I_0 - I_7	Inputs (74F244)	1.0 / 2.667 ⁽²⁾	20 μ A / -1.6mA
\overline{O}_0 - \overline{O}_7, O_0 - O_7	Outputs	600 / 106.6 (80)	-12mA / 64mA (48mA)

Note:

2. Worst-case 74F240 enabled; 74F244 disabled.

Truth Tables

74F240

\overline{OE}_1	D_{1n}	O_{1n}	\overline{OE}_2	D_{2n}	O_{2n}
H	X	Z	H	X	Z
L	H	L	L	H	L
L	L	H	L	L	H

74F244

\overline{OE}_1	D_{1n}	O_{1n}	\overline{OE}_2	D_{2n}	O_{2n}
H	X	Z	H	X	Z
L	H	H	L	H	H
L	L	L	L	L	L

H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial

Z = High Impedance

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
T_{STG}	Storage Temperature	-65°C to +150°C
T_A	Ambient Temperature Under Bias	-55°C to +125°C
T_J	Junction Temperature Under Bias	-55°C to +150°C
V_{CC}	V_{CC} Pin Potential to Ground Pin	-0.5V to +7.0V
V_{IN}	Input Voltage ⁽³⁾	-0.5V to +7.0V
I_{IN}	Input Current ⁽³⁾	-30mA to +5.0mA
V_O	Voltage Applied to Output in HIGH State (with $V_{CC} = 0V$)	
	Standard Output	-0.5V to V_{CC}
	3-STATE Output	-0.5V to 5.5V
	Current Applied to Output in LOW State (Max.)	twice the rated I_{OL} (mA)
	ESD Last Passing Voltage (Min.)	4000V

Note:

3. Either voltage limit or current limit is sufficient to protect inputs.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating
T_A	Free Air Ambient Temperature	0°C to +70°C
V_{CC}	Supply Voltage	+4.5V to +5.5V

DC Electrical Characteristics

Symbol	Parameter	V_{CC}	Conditions	Min.	Typ.	Max.	Units
V_{IH}	Input HIGH Voltage		Recognized as a HIGH Signal	2.0			V
V_{IL}	Input LOW Voltage		Recognized as a LOW Signal			0.8	V
V_{CD}	Input Clamp Diode Voltage	Min.	$I_{IN} = -18\text{mA}$			-1.2	V
V_{OH}	Output HIGH Voltage	10% V_{CC}	Min. $I_{OH} = -3\text{mA}$	2.4			V
		10% V_{CC}		$I_{OH} = -15\text{mA}$	2.0		
		5% V_{CC}		$I_{OH} = -3\text{mA}$	2.7		
V_{OL}	Output LOW Voltage	10% V_{CC}	Min. $I_{OL} = 64\text{mA}$			0.55	V
I_{IH}	Input HIGH Current	Max.	$V_{IN} = 2.7\text{V}$			5.0	μA
I_{BVI}	Input HIGH Current Breakdown Test	Max.	$V_{IN} = 7.0\text{V}$			7.0	μA
I_{CEX}	Output HIGH Leakage Current	Max.	$V_{OUT} = V_{CC}$			50	μA
V_{ID}	Input Leakage Test	0.0	$I_{ID} = 1.9\mu\text{A}$	4.75			V
			All Other Pins Grounded				
I_{OD}	Output Leakage Circuit Current	0.0	$V_{IOD} = 150\text{mV}$			3.75	μA
			All Other Pins Grounded				
I_{IL}	Input LOW Current	Max.	$V_{IN} = 0.5\text{V}$ ($\overline{OE}_1, \overline{OE}_2, OE_2, D_n$ (74F240))			-1.0	mA
			$V_{IN} = 0.5\text{V}$ (D_n (74F244))			-1.6	
I_{OZH}	Output Leakage Current	Max.	$V_{OUT} = 2.7\text{V}$			50	μA
I_{OZL}	Output Leakage Current	Max.	$V_{OUT} = 0.5\text{V}$			-50	μA
I_{OS}	Output Short-Circuit Current	Max.	$V_{OUT} = 0\text{V}$	-100		-225	mA
I_{ZZ}	Bus Drainage Test	0.0V	$V_{OUT} = 5.25\text{V}$			500	μA
I_{CCH}	Power Supply Current (74F240)	Max.	$V_O = \text{HIGH}$		19	29	mA
I_{CCL}	Power Supply Current (74F240)	Max.	$V_O = \text{LOW}$		50	75	mA
I_{CCZ}	Power Supply Current (74F240)	Max.	$V_O = \text{HIGH Z}$		42	63	mA
I_{CCH}	Power Supply Current (74F244)	Max.	$V_O = \text{HIGH}$		40	60	mA
I_{CCL}	Power Supply Current (74F244)	Max.	$V_O = \text{LOW}$		60	90	mA
I_{CCZ}	Power Supply Current (74F244)	Max.	$V_O = \text{HIGH Z}$		60	90	mA

AC Electrical Characteristics

Symbol	Parameter	$T_A = +25^\circ\text{C}$, $V_{CC} = +5.0\text{V}$, $C_L = 50\text{pF}$			$T_A = -55^\circ\text{C to } +125^\circ\text{C}$, $V_{CC} = 5.0\text{V}$, $C_L = 50\text{pF}$		$T_A = 0^\circ\text{C to } +70^\circ\text{C}$, $V_{CC} = 5.0\text{V}$, $C_L = 50\text{pF}$		Units
		Min.	Typ.	Max.	Min.	Max.	Min.	Max.	
t_{PLH} , t_{PHL}	Propagation Delay Data to Output (74F240)	3.0	5.1	7.0	3.0	9.0	3.0	8.0	ns
		2.0	3.5	4.7	2.0	6.0	2.0	5.7	
t_{PZH} , t_{PZL}	Output Enable Time (74F240)	2.0	3.5	4.7	2.0	6.5	2.0	5.7	ns
		4.0	6.9	9.0	4.0	10.5	4.0	10.0	
t_{PHZ} , t_{PLZ}	Output Disable Time (74F240)	2.0	4.0	5.3	2.0	6.5	2.0	6.3	ns
		2.0	6.0	8.0	2.0	12.5	2.0	9.5	
t_{PLH} , t_{PHL}	Propagation Delay, Data to Output (74F244)	2.5	4.0	5.2	2.0	6.5	2.5	6.2	ns
		2.5	4.0	5.2	2.0	7.0	2.5	6.5	
t_{PZH} , t_{PZL}	Output Enable Time (74F244)	2.0	4.3	5.7	2.0	7.0	2.0	6.7	ns
		2.0	5.4	7.0	2.0	8.5	2.0	8.0	
t_{PHZ} , t_{PLZ}	Output Disable Time (74F244)	2.0	4.5	6.0	2.0	7.0	2.0	7.0	ns
		2.0	4.5	6.0	2.0	7.5	2.0	7.0	

Physical Dimensions

Dimensions are in inches (millimeters) unless otherwise noted.

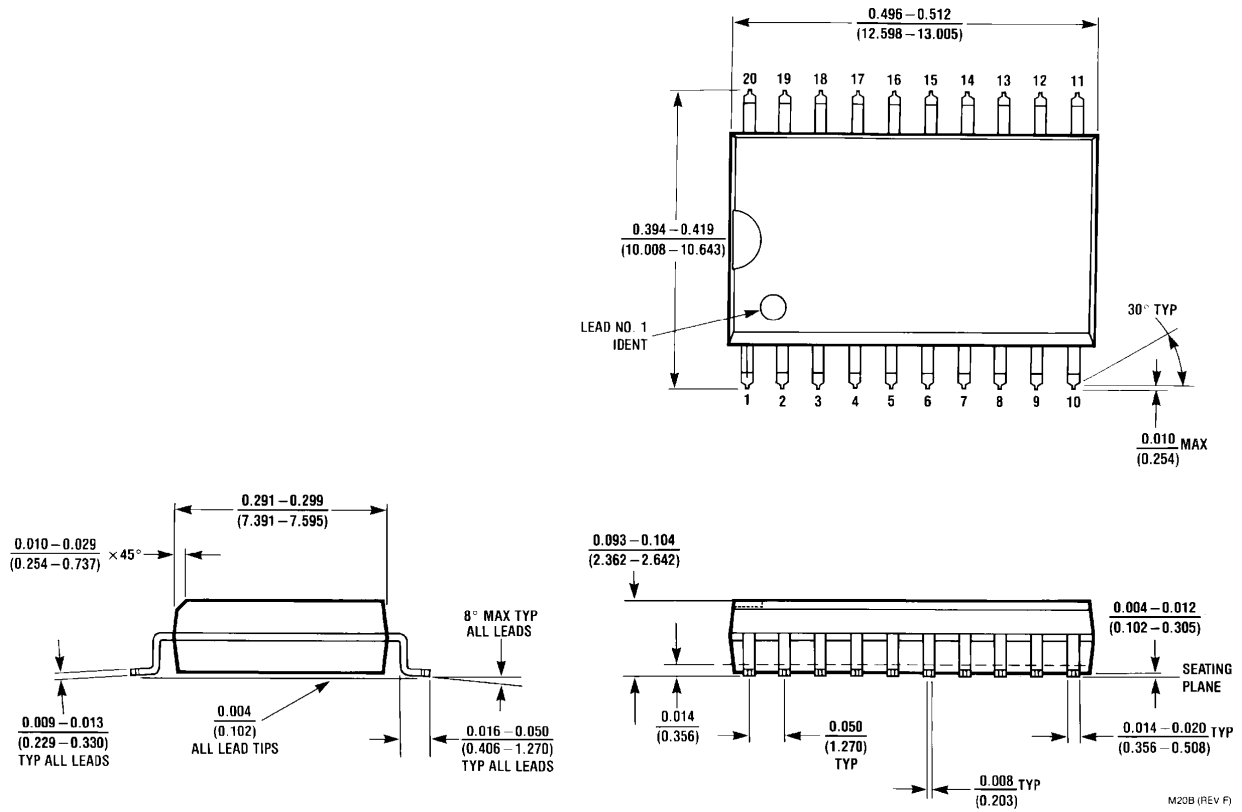
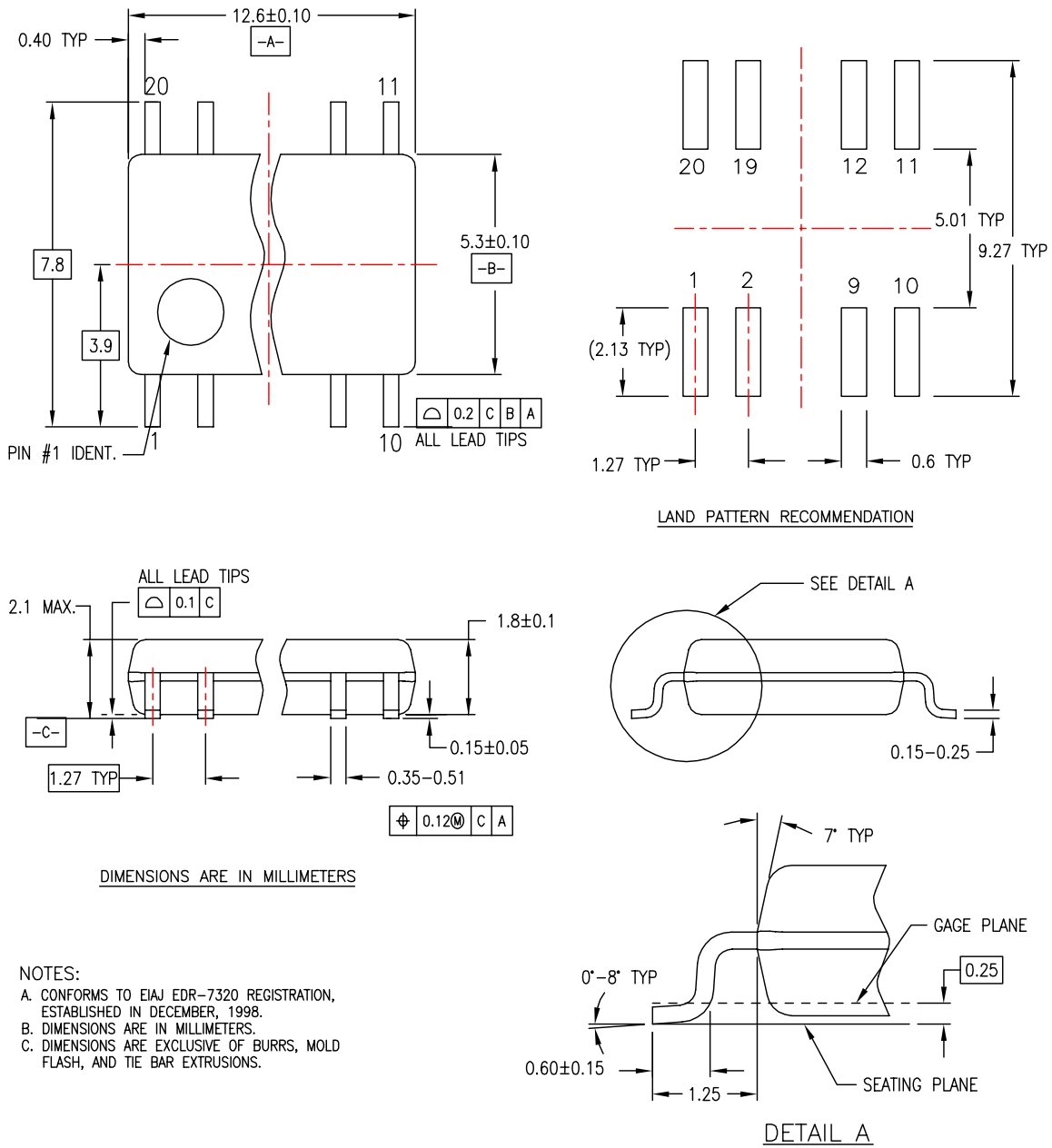


Figure 1. 20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
Package Number M20B

M20B (REV F)

Physical Dimensions (Continued)

Dimensions are in millimeters unless otherwise noted.



NOTES:

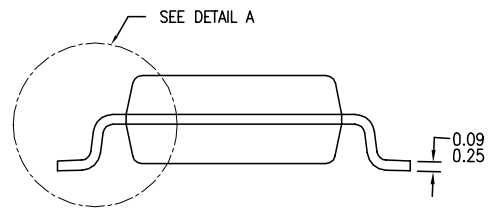
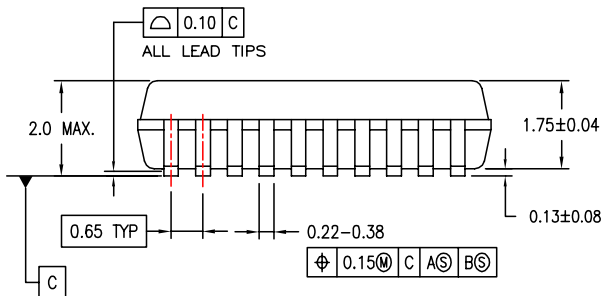
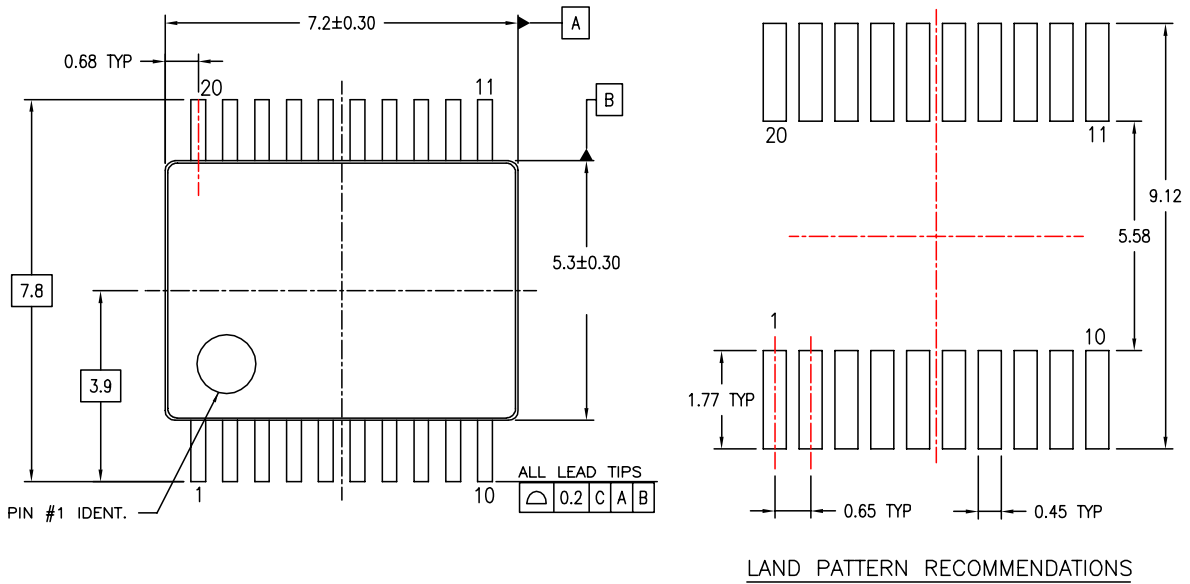
- A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
- B. DIMENSIONS ARE IN MILLIMETERS.
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M20DREV C

Figure 2. 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide Package Number M20D

Physical Dimensions (Continued)

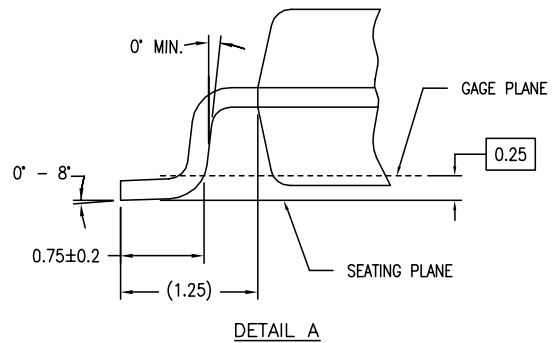
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- D. DIMENSIONS AND TOLERANCES PER ASME Y14.5M - 1994.



MSA20REVB

Figure 3. 20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide Package Number MSA20

Physical Dimensions (Continued)

Dimensions are in inches (millimeters) unless otherwise noted.

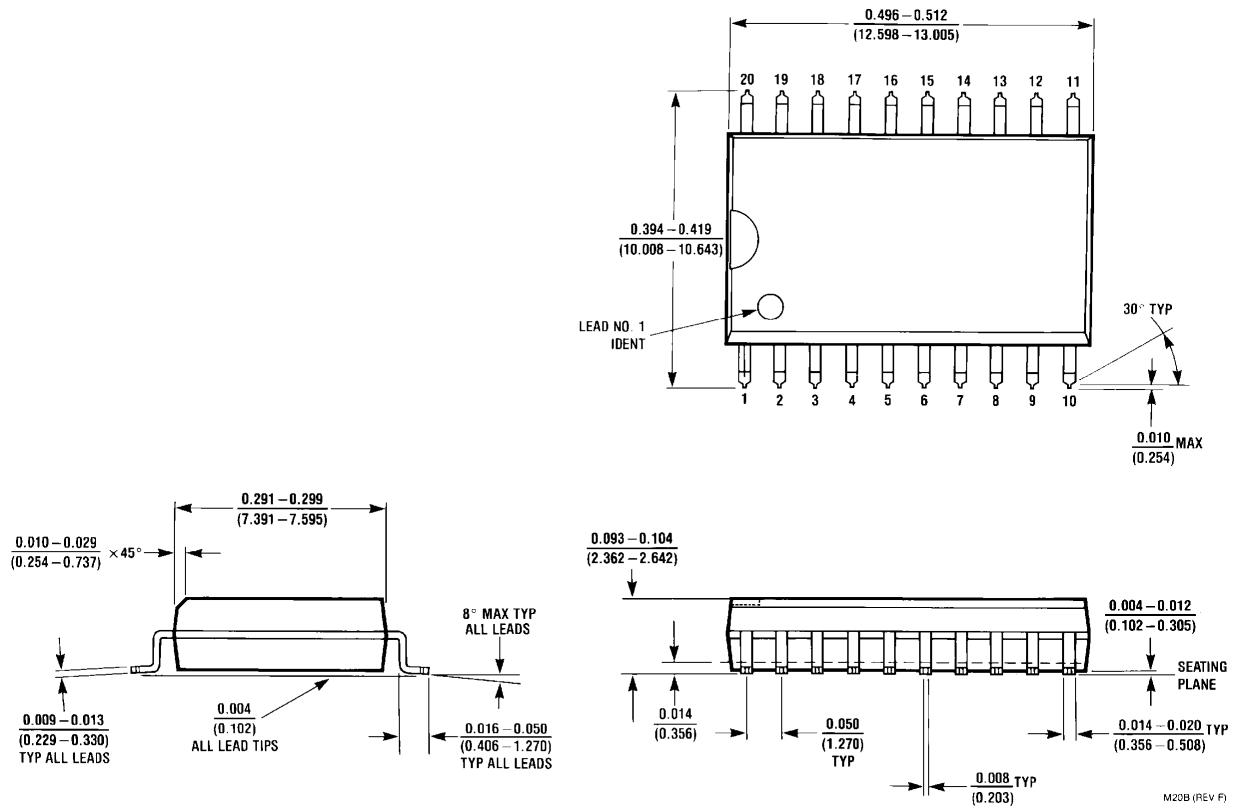



Figure 4. 20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide Package Number N20A



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